

METHOD FOR ELIMINATING DEVELOPMENT RELATED DEFECTS  
IN PHOTORESIST MASKS

ABSTRACT

Sub 97  
5 Polymer blobs that are development related defects are  
substantially eliminated in the patterned photoresist masks by  
a heat treatment of the wafer performed at the development  
step in two different manners according to the present  
invention. In the first method, after the development has been  
performed as standard, the wafer is heated at 140°C and before  
10 cooling takes place, it is rinsed with deionized water (DIW)  
at room temperature. In the second method, the wafer is either  
developed as standard but rinsed with 60°C DIW instead of 22°C  
DIW or, after standard development, it is submitted to an  
extra rinse step with 60°C DIW.

15 FIG. 6